

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	13	("5455894" "2003045131" "6707545" "6308107" "2003099112").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 11:00
S2	11	("5455894" "20030045131" "6707545" "6308107" "2003099112").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 11:09
S3	0	S2 and clock with signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 11:10
S4	7	S2 and signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 11:12
S5	0	S2 and clock	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 11:10
S6	2	S2 and timer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 11:12
S7	4315	(700/121,204,112,99,247,258, 259,254 414/937,940).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:13
S8	686	S7 and (semiconductor wafer) with (fabricat\$3) and (inspect\$3 monitor\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:19
S9	120	S7 and (semiconductor wafer) with (fabricat\$3) with (inspect\$3 monitor\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:20

S10	3	S7 and (semiconductor wafer) with (fabricat\$3) with (inspect\$3 monitor\$3) and clock near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:23
S11	0	S7 and (semiconductor wafer) with (fabricat\$3) with (inspect\$3 monitor\$3) and clock near system	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:21
S12	17	S7 and (semiconductor wafer) with (fabricat\$3) and (inspect\$3 monitor\$3) and (scanner\$1 camera\$1) and clock\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:26
S13	7	S7 and (semiconductor wafer) with (fabricat\$3) and (inspect\$3 monitor\$3) and (scanner\$1 camera\$1) and (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:30
S14	341	(semiconductor wafer) with (fabricat\$3) and (inspect\$3 monitor\$3) and (scanner\$1 camera\$1) and (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:30
S15	0	(semiconductor wafer) with (fabricat\$3) and (inspect\$3 monitor\$3) and (scanner\$1 camera\$1) and (clock time) with delay with (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:31
S16	15	(semiconductor wafer) with (fabricat\$3) and (inspect\$3 monitor\$3) and (scanner\$1 camera\$1) and (clock time) with (deviation variation) with (adjustment compensation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:31
S17	23	oh near hilario.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:33

S18	59	("4441124" "4449818" "4499595" "4626101" "4732473" "4772126" "4893932" "4898471" "4920385" "4941980" "4969748" "4977330" "4989973" "5058178" "5120034" "5164603" "5177559" "5186718" "5233191" "5274434" "5317656" "5416594" "5463459" "5465152" "5479252" "5483138" "5486919" "5563798" "5637881" "5644393" "5646725" "5659172" "5663569" "5694214" "5699447" "5737072" "5748305" "5774222" "5781230" "5797317" "5801824" "5805278" "5808735" "5818576" "5822213" "5834758" "5861952" "5864394" "5883710" "5889593" "5900633" "5903342" "5909276" "5940175" "6012966" "6020957" "6236903" "6342704" "6373565").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/03 12:41
S19	9	S18 and clock	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:45
S20	0	S18 and timing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:45
S21	51	S18 and time	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 12:46
S22	12	S18 and time with (compensat\$3 delay deviation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 13:04

S23	19	S18 and (track\$3 convey\$3 transport\$3) with wafer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 13:06
S24	17	S18 and (track\$3 convey\$3 transport\$3) with wafer\$1 and time	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 13:06
S25	9	S18 and (track\$3 convey\$3 transport\$3) with wafer\$1 and time and (compensat\$3 delay\$3 deviation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/03 13:07
S26	1	(semiconductor and fabrication). ab. and (scanner\$1 camera) with system adj clock	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:53
S27	0	(semiconductor and fabrication). ab. and (scanner\$1 camera) with operating with (clock pulse\$1) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:54
S28	0	(semiconductor and fabrication). ab. and (scanner\$1 camera) and operating with (clock pulse\$1) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:54
S29	1	(semiconductor and fabrication). ab. and (scan\$\$5 camera\$1) and operating with (clock pulse\$1) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:54
S30	9	(semiconductor and fabrication). ab. and (scan\$\$5 camera\$1) and operat\$3 with (clock pulse\$1) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:57
S31	94	(semiconductor and fabrication). ab. and (scan\$\$5 camera\$1) near system	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 13:58
S32	9	(semiconductor and fabrication). ab. and (scan\$\$5 camera\$1) near system and (clock pulse\$1) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:01
S33	1	2004-699555.NRAN.	DERWENT	OR	ON	2006/02/06 14:00

S34	8	(semiconductor and fabrication). ab. and (scan\$5) near system and (track\$3 near system)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:02
S35	847	(semiconductor and fabrication). ab. and inspect\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:02
S36	55	(semiconductor and fabrication). ab. and inspect\$3 and time adj delay\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:03
S37	39	(semiconductor and fabrication and inspect\$3).ab. and time adj delay\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:04
S38	39	(semiconductor and fabrication and inspect\$3).ab. and time adj delay\$3 and (scan\$5 camera\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:07
S39	1	(semiconductor and fabrication and inspect\$3).ab. and time adj delay\$3 and (scan\$5 camera\$1) and time near (calculation computation computing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:08
S40	0	(semiconductor and fabrication and inspect\$3).ab. and time adj delay\$3 with (calculation computation computing) and (scan\$5 camera\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:09
S41	0	(semiconductor and fabrication and inspect\$3).ab. and time adj delay\$3 same (calculation computation computing) and (scan\$5 camera\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:09
S42	6	(semiconductor and fabrication and inspect\$3).ab. and time same (calculation computation computing) and (scan\$5 camera\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:11
S44	518	(semiconductor and fabrication and inspect\$3) and time with (calculation computation computing) and (scan\$5 camera\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:12

S45	4	(semiconductor and fabrication and inspect\$3) and time with (calculation computation computing) same (scan\$5) with operat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:25
S46	1503	(semiconductor and fabrication and inspect\$3) and scanner	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:25
S47	5	(semiconductor and fabrication and inspect\$3 and scanner).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:29
S48	1699	(semiconductor and fabrication and inspect\$3).ab. operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:29
S49	423	(semiconductor and fabrication and inspect\$3).ab. operating near scanner\$1 with (clock pulse) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:36
S50	419	(semiconductor and fabrication and inspect\$3).ab. operating near scanner\$1 with response with (clock pulse) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:32
S51	0	(semiconductor and fabrication and inspect\$3).ab. and operating near scanner\$1 with response with (clock pulse) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:35
S52	0	(semiconductor and fabrication and inspect\$3).ab. and operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:32
S53	4	semiconductor and fabrication and inspect\$3 and operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:32
S54	0	(wafer\$1 and inspect\$3).ab. and operating near scanner\$1 with response with (clock pulse) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:36

S55	0	(wafer\$1 and inspect\$3).ab. and operating near scanner\$1 with (clock pulse) near signal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:37
S56	0	(wafer\$1 and inspect\$3).ab. and operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:37
S57	0	(wafer\$1 and monitor\$3).ab. and operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:37
S58	0	(semiconductor and monitor\$3).ab. and operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:38
S59	0	(semiconductor and inspect\$3).ab. and operating near scanner\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:38
S60	10	(semiconductor and inspect\$3).ab. and scanner\$1 near system	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:42
S61	198	(semiconductor and inspect\$3).ab. and time near delay\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:42
S62	8	(semiconductor and inspect\$3).ab. and time near delay\$3 and time near (calculation calculating calculated computing computation calculates computes computed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:44
S63	0	(semiconductor and inspect\$3).ab. and scan\$4 near delay\$3 and time near (calculation calculating calculated computing computation calculates computes computed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:44
S64	9	semiconductor and inspect\$3 and scan\$4 near delay\$3 and time near (calculation calculating calculated computing computation calculates computes computed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/06 14:44

S65	12	("5769952" "5368054" "6745637" "6267122" "20010024691").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/07 16:06
S66	22	("5769952" "5368054" "6745637" "6267122" "20010024691" "5672239" "5776360" "6467491" "6460552" "5849582").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/07 16:06
S67	15	("4472783" "4561060" "4665492" "4708574" "4827423" "5231585" "5455894" "5467285" "5658123" "5835377" "5838566" "5924833" "6035245" "6108585" "6157866").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/07 16:12
S68	7	S67 and delay\$3 and time	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 11:33
S69	2	S67 and delay\$3 and time and (scan\$4 monitor\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/07 16:30
S70	29	semiconductor and inspection near scanner	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 11:34
S71	0	semiconductor and inspection near scanner and number adj of adj wafer\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 11:35
S72	2	semiconductor and inspection near scanner and wafer\$1 with count\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 11:40

S73	35	("3,887,762" "4,253,112" "4,484,081" "4,589,140" "4,953,224" "4,979,223" "4,984,282" "4,985,927" "5,001,764" "5,018,212" "5,046,110" "5,095,447" "5,119,434" "4,999,785" "5,495,337" "5,517,234" "5,608,453" "5,621,811" "5,659,630" "4,445,137" "4,174,514" "5,537,669" "4,979,223" "5,357,632" "4,181,936" "6,081,659" "4,484,349" "6,578,961" "6,130,967" "5,315,700" "6,366,687" "5,434,629" "4,850,027" "5,581,777" "20020114506" "20020051565"). pn.	US-PGPUB; USPAT	OR	ON	2006/02/08 11:41
S74	15	S73 and delay with time	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:24
S75	577	wafer adj per adj hour	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:25
S76	577	wafers adj per adj hour	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:25
S77	2	(moving carrying transporting) near5 (wafer\$ adj per adj hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:27
S78	0	(moving carrying transporting) near5 (wafer\$ near hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:27
S79	0	(moving carrying transporting conveying) near5 (wafer\$ near hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:28
S80	5	(moving carrying transporting conveying) near5 (wafer\$ near3 hour)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 14:57

S81	0	(semiconductor with fabrication) and process\$3 with speed and (number adj of amount adj of) near5 wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:44
S82	0	(semiconductor with fabrication) and process\$3 with speed and (number adj of amount adj of) with wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:44
S83	0	(semiconductor with fabrication) and scan\$4 and (number adj of amount adj of) with wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:45
S84	0	(semiconductor with fabrication) and scan\$4 and (number adj of amount adj of) adj wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:45
S85	9590	(semiconductor with fabrication) and scan\$4 and wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:45
S86	2322	(semiconductor with fabrication) and scan\$4 and (number amount) near5 wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:45
S87	0	(semiconductor with fabrication) and scan\$4 and (number amount) adj of near5 wafers	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:46
S88	989	(semiconductor with fabrication) and scan\$4 and (number amount) near3 wafers and speed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:46
S89	191	(semiconductor with fabrication) and scan\$4 and (number amount) near3 wafers and scan\$4 near3 speed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:47
S90	20	(semiconductor with fabrication) and scan\$4 with (number amount) near3 wafers and scan\$4 near3 speed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:52

S91	65	(semiconductor with fabrication) and scan\$4 with (number amount) near3 wafers and throughput	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	ON	2006/02/08 15:53
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